

SN54LS465 THRU SN74LS468 OCTAL BUFFERS WITH 3-STATE OUTPUTS

SDLS179 – JANUARY 1981 – REVISED MARCH 1988

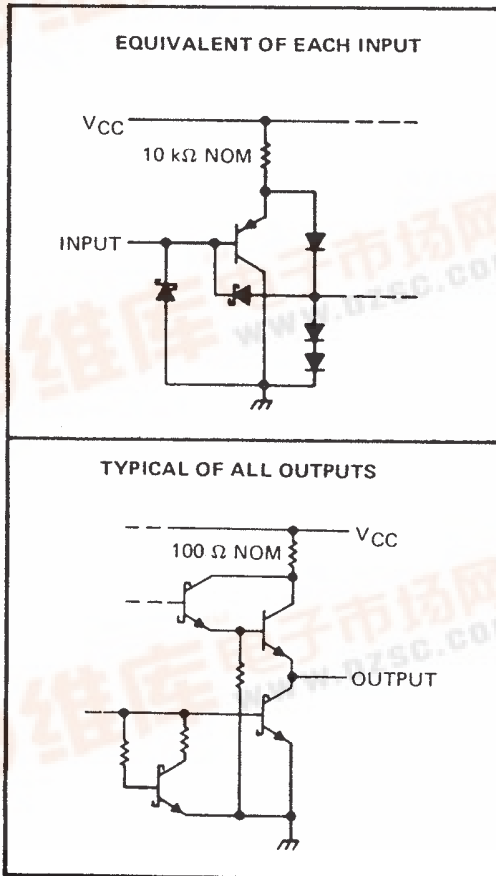
- Mechanically and Functionally Interchangeable With DM71/81LS95 thru DM71/81LS98
- P-N-P Inputs Reduce Bus Loading
- 3-State Outputs Rated at I_{OL} of 12 mA and 24 mA for 54LS and 74LS, Respectively

DEVICE	DATA PATH
'LS465	True
'LS466	Inverting
'LS467	True
'LS468	Inverting

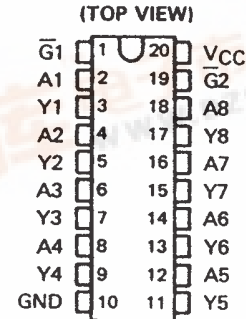
description

These octal buffers utilize the latest low-power Schottky technology. The 'LS465 and 'LS466 have a two-input active-low AND enable gate controlling all eight data buffers. The 'LS467 and 'LS468 have two separate active-low enable inputs each controlling four data buffers. In either case, a high level on any $\bar{G}$ places the affected outputs at high impedance.

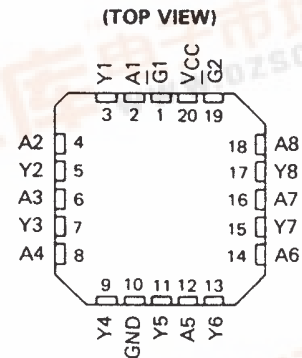
schematics of inputs and outputs



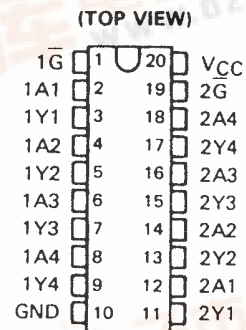
SN54LS465 AND SN54LS466 . . . J PACKAGE SN74LS465 AND SN74LS466 . . . DW OR N PACKAGE



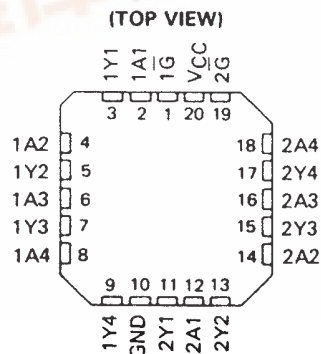
SN54LS465 AND SN54LS466 . . . FK PACKAGE



SN54LS467 AND SN54LS468 . . . J PACKAGE SN74LS467 AND SN74LS468 . . . DW OR N PACKAGE



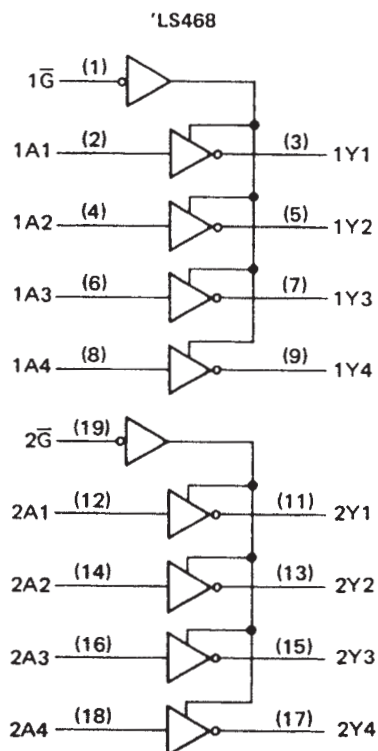
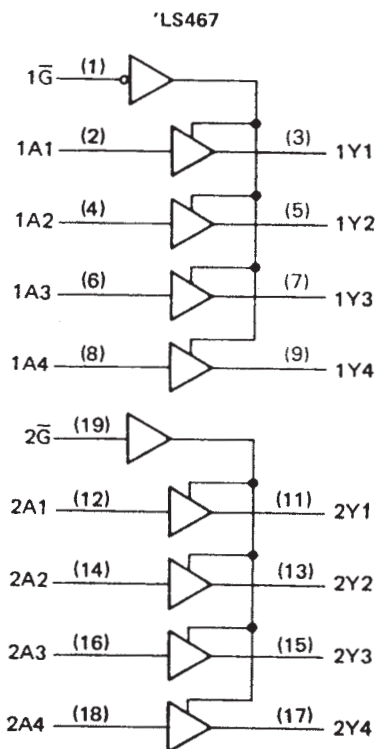
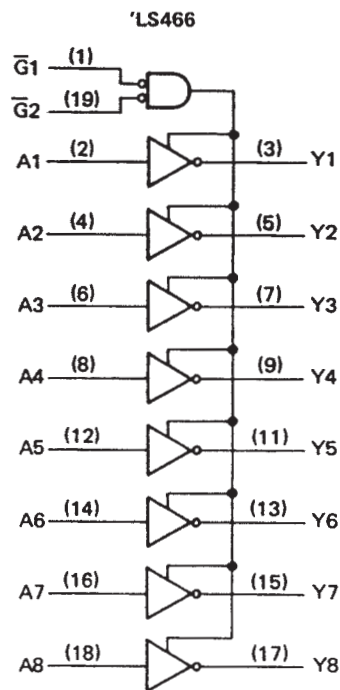
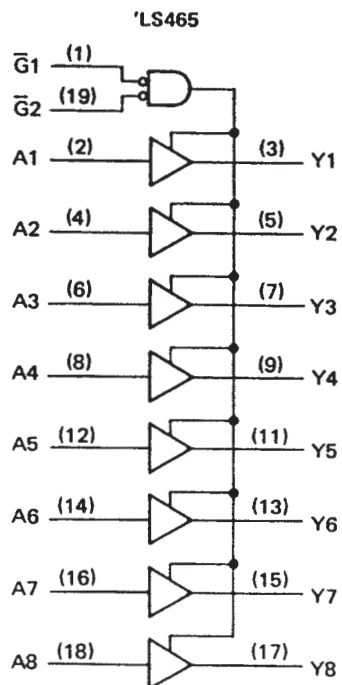
SN54LS467 AND SN54LS468 . . . FK PACKAGE



SN54LS465 THRU SN54LS468, SN74LS465 THRU SN74LS468 OCTAL BUFFERS WITH 3-STATE OUTPUTS

SDLS179 – JANUARY 1981 – REVISED MARCH 1988

logic diagrams (positive logic)

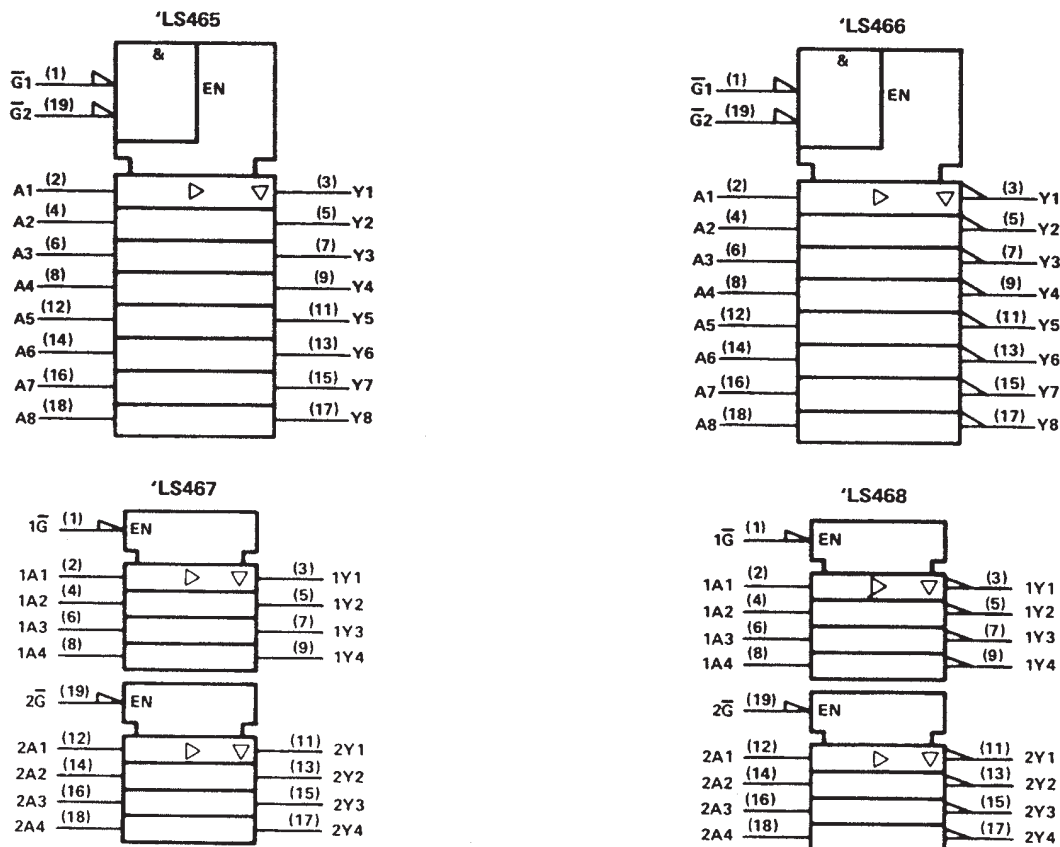


Pin numbers shown are for DW, J, and N packages.

SN54LS465 THRU SN54LS468, SN74LS465 THRU SN74LS468 OCTAL BUFFERS WITH 3-STATE OUTPUTS

SDLS179 – JANUARY 1981 – REVISED MARCH 1988

logic symbols†



†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for DW, J, and N packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	7 V
Off-state output voltage	5.5 V
Operating free-air temperature range: SN54LS465 thru SN54LS468	-55°C to 125°C
SN74LS465 thru SN74LS468	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

	SN54LS'			SN74LS'			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			-1			-2.6	mA
Low-level output current, I_{OL}			12			24	mA
Operating free-air temperature, T_A	-55		125	0		70	°C

SN54LS465 THRU SN54LS468, SN74LS465 THRU SN74LS468

OCTAL BUFFERS WITH 3-STATE OUTPUTS

SDLS179 – JANUARY 1981 – REVISED MARCH 1988

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54LS'			SN74LS'			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IH}	High-level input voltage			2			2			V
V _{IL}	Low-level input voltage			0.7			0.8			V
V _{IK}	Input clamp voltage	V _{CC} = MIN, I _I = -18 mA		-1.5			-1.5			V
V _{OH}	High-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = V _{IL} max	I _{OH} = -1 mA I _{OH} = -2.6 mA	2.4	3.3		2.4	3.1		V
V _{OL}	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = V _{IL} max	I _{OL} = 12 mA I _{OL} = 24 mA	0.25	0.4		0.25	0.4		V
I _{OZH}	Off-state output current, high-level voltage applied	V _{CC} = MAX, V _{IH} = 2 V, V _{IL} = V _{IL} max, V _O = 2.7 V		20			20			µA
I _{OZL}	Off-state output current, low-level voltage applied	V _{CC} = MAX, V _{IH} = 2 V, V _{IL} = V _{IL} max, V _O = 0.4 V		-20			-20			µA
I _I	Input current at maximum input voltage	V _{CC} = MAX, V _I = 7 V		0.1			0.1			mA
I _{IH}	High-level input current	V _{CC} = MAX, V _I = 2.7 V		20			20			µA
I _{IL}	Low-level input current	V _{CC} = MAX, V _I = 0.4 V		-0.2			-0.2			mA
I _{OS}	Short-circuit output current§	V _{CC} = MAX, V _O = 0 V		-30	-130		-30	-130		mA
I _{CC}	Supply current	V _{CC} = MAX	Outputs low	19	32		19	32		mA
			Outputs high	13	22		13	22		
			Output Hi-Z	22	37		22	37		
			Outputs low	14	23		14	23		
			Outputs high	6	10		6	10		
			Outputs Hi-Z	17	28		17	28		

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C, see note 2

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS465, 'LS467			'LS466, 'LS468			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t _{PLH}	A _i	Y _i	R _L = 667 Ω, C _L = 45 pF		9	15		7	12	ns
t _{PHL}	A _i	Y _i			12	18		9	15	ns
t _{PZH}	$\bar{G}$ ↓	Y			25	40		25	40	ns
t _{PZL}	$\bar{G}$ ↓	Y			29	45		29	45	ns
t _{PHZ}	$\bar{G}$ ↑	Y	R _L = 667 Ω, C _L = 5 pF		25	40		25	40	ns
t _{PLZ}	$\bar{G}$ ↑	Y			30	45		30	45	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LS465DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS465DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS465DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS465DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS465DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS465DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS465DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS465N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS465N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS465NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS465NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS466DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SN74LS466DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SN74LS466N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

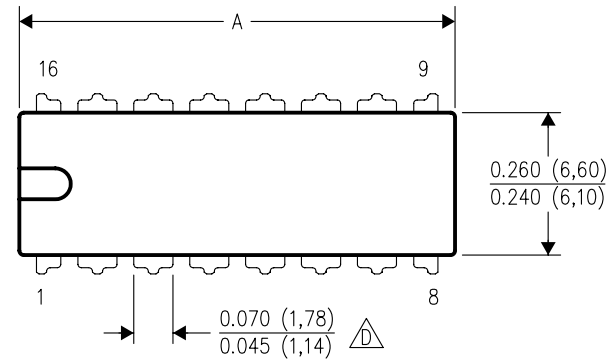
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

MECHANICAL DATA

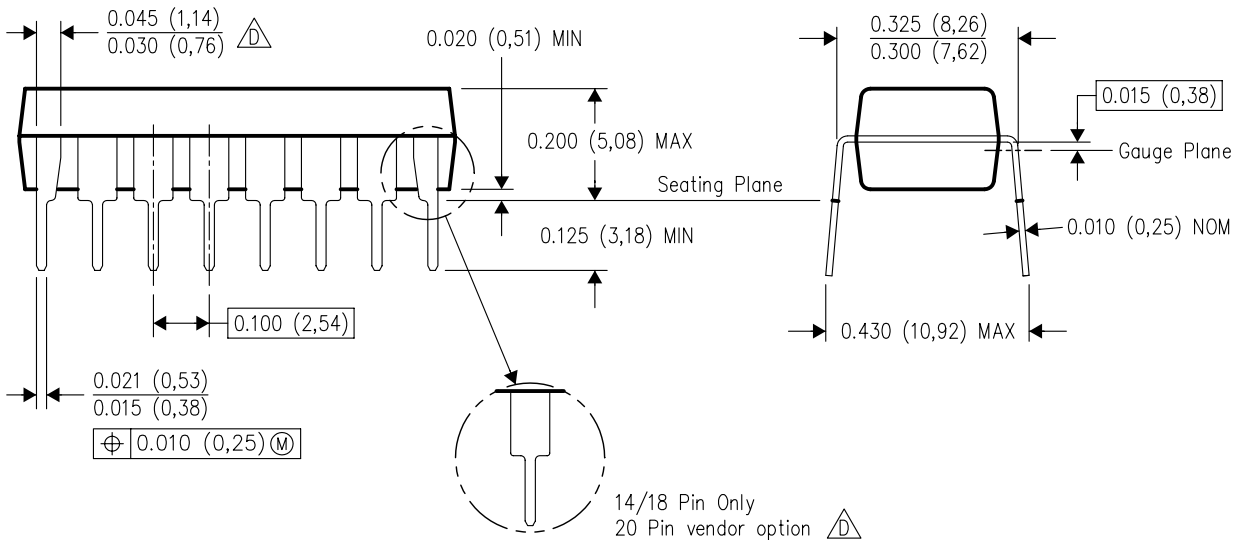
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



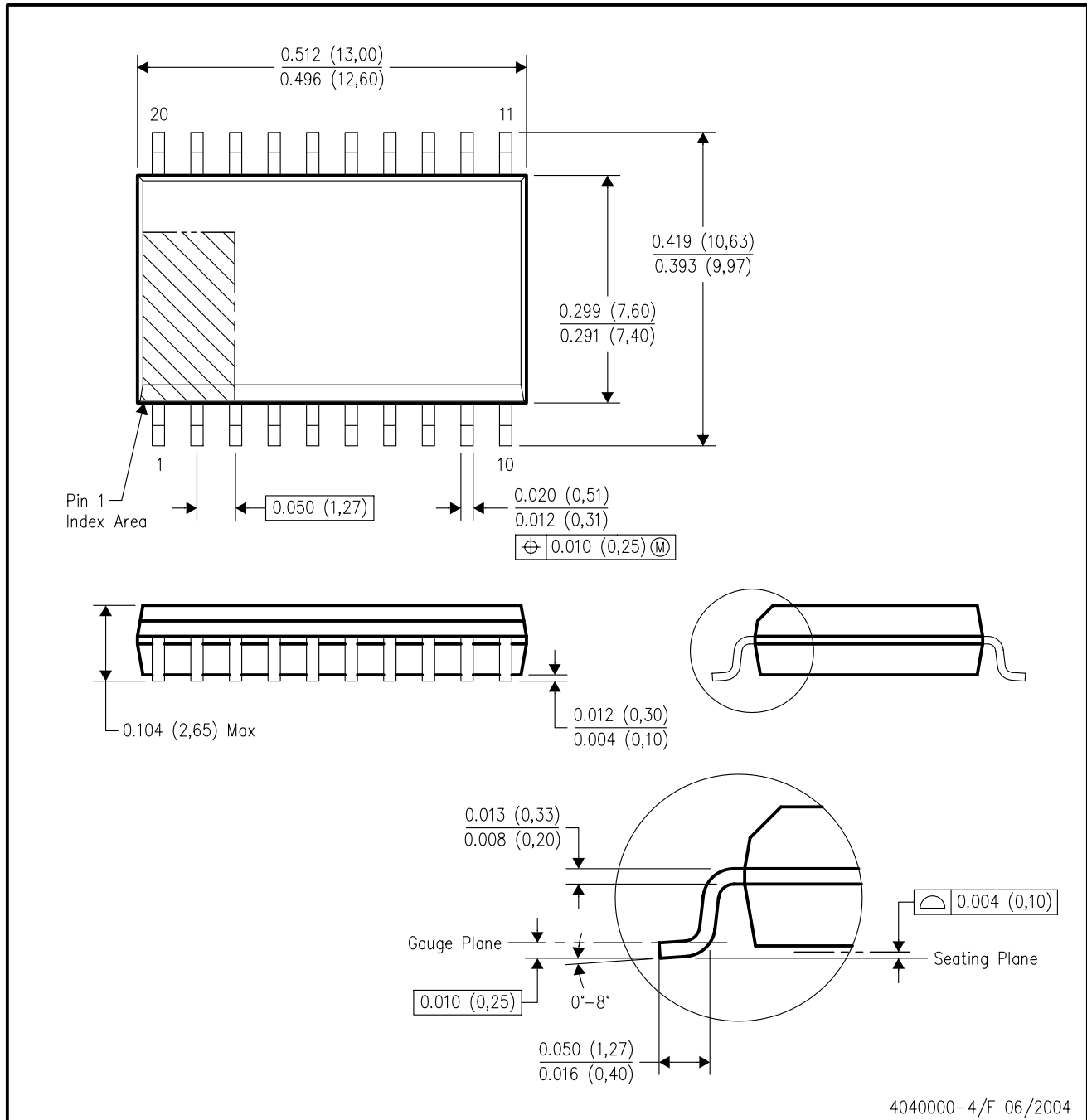
4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



4040000-4/F 06/2004

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265